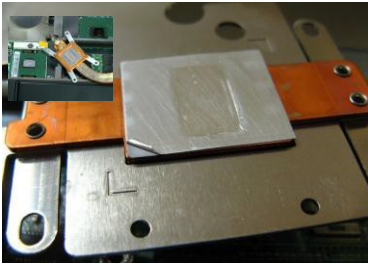


TIC™800A-AL series is low melting point thermal interface material. At 50°C, TIC™800A-AL series begins to soften and flow, filling the microscopic irregularities of both the thermal solution and the integrated circuit package surface, thereby reducing thermal resistance. TIC™800A-AL series is a flexible solid at room temperature and freestanding without reinforcing components that reduce thermal performance.

TIC™800A-AL Series shows no thermal performance degradation after 1,000 hours@130°C, or after 500 cycles, from -25°C to 125°C. The material softens and does not fully change state resulting in minimal migration (pump out) at operating temperatures.



Applications Include:

- » High Frequency Microprocessors
- » Notebook and Desktop PCs
- » Computer Servers
- » Memory Modules
- » Cache Chips
- » IGBTs

For Lowest Thermal Resistance :

- » **0.021°C-in²/W** thermal resistance
- » Naturally tacky at room temperature, no adhesive required
- » No heat sink preheating required

Typical Properties of TIC™800A-AL Series

Product Name	TIC™805A-AL	TIC™808A-AL	TIC™810A-AL	TIC™820A-AL	Test Method
Color	Gray / Silver	Gray / Silver	Gray / Silver	Gray / Silver	Visual
Thickness	0.005" (0.126mm)	0.008" (0.203mm)	0.010" (0.254mm)	0.020" (0.508mm)	
Thickness Tolerance	±0.0008" (±0.019mm)	±0.0008" (±0.019mm)	±0.0012" (±0.030mm)	±0.0020" (±0.050mm)	
Density	2.5g/cc				Helium Pycnometer
Temperature range	-25°C ~ 125°C				
Phase Change Softening Temperature	50°C ~ 60°C				
Thermal Conductivity	2.5 W/mK				ASTM D5470 (modified)
Thermal Impedance @ 50 psi(345 KPa)	0.063°C-in²/W 0.40°C-cm²/W	0.08°C-in²/W 0.52°C-cm²/W	0.097°C-in²/W 0.63°C-cm²/W	0.175°C-in²/W 1.13°C-cm²/W	ASTM D5470 (modified)

Standard Thicknesses:

0.005"(0.127mm) 0.008"(0.203mm) 0.010"(0.254mm) 0.020"(0.508mm)

Consult the factory alternate thickness.

Standard Sizes:

10" x 16"(254mm x 406mm)

TIC™800 series are supplied with a white release paper and a bottom liner. TIC800™ series is available in kiss cut an extended pull tab liner or individual die cut shapes.

Peressure Sensitive Adhesive:

Peressure Sensitive Adhesive is not applicable for TIC™800 series products.

Reinforcement:

No reinforcement is necessary.

Gap Fillers

Phase Change Materials

Thermally Conductive Insulators

Thermally Conductive Greases

Thermally

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